

Product Change Notification

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Printed form FC32S00970 / Rev L

Product Change Notification Number : GC151551

Date: 27 Mai 2015

This notification replaced previously released GC144851

Title: PC8548 rev3 migration to lead-free C4 bumps

Product Identification:

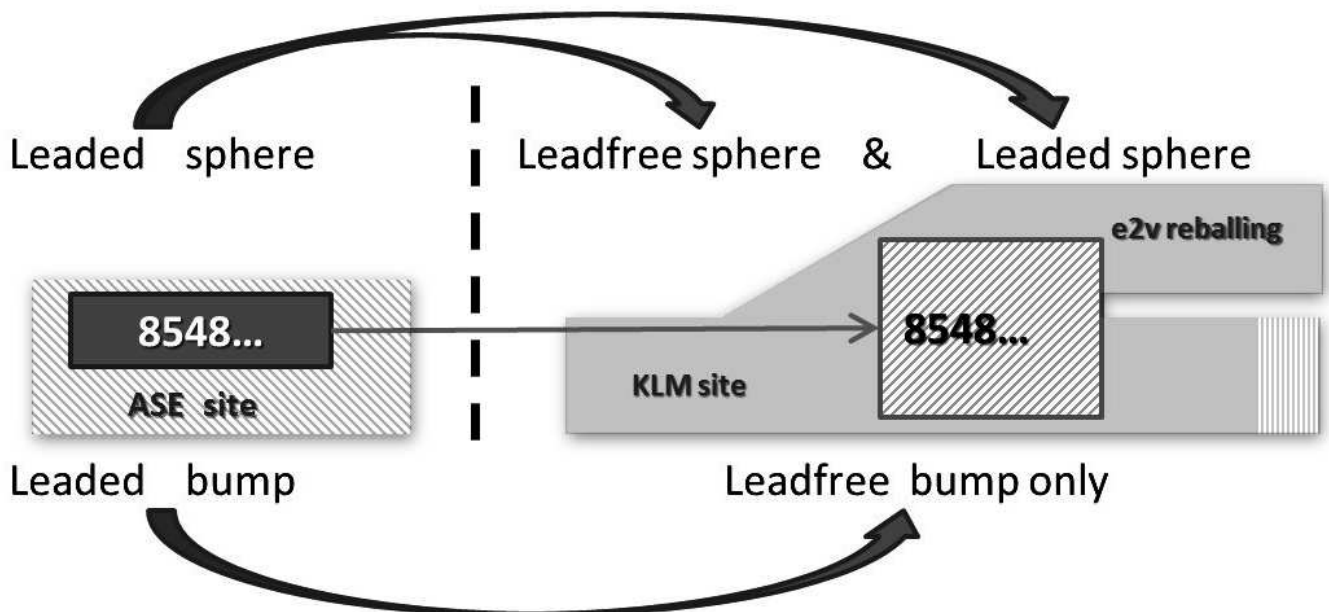
Affected Part Numbers **PC(X)8548EFZFUAUJD, PC8548EMZFAUJD-EP**

Reason for Change:

- | | | | |
|--------------------------------|--|--|--|
| <input type="checkbox"/> Other | <input type="checkbox"/> Design | <input type="checkbox"/> Processing | <input type="checkbox"/> Logistics |
| | <input checked="" type="checkbox"/> Manufacturing Location | <input type="checkbox"/> Quality/Reliability | <input checked="" type="checkbox"/> Material |

Change Description:

- The assembly line for PC8548 is changing from ASE to Freescale KLM site (Kuala Lumpur Malaysia).
- The C4 die bumps are changing from leaded (90/10 PbSn) to lead free (SAC) die bumps.
- Since Freescale is stopping the manufacturing of the leaded version of this device, the e2v leaded devices with leaded solder spheres (ball) will be manufactured using a deballing/reballing process applied on Freescale lead free devices.



This change does not affect the fit, form, functions of the part and the electrical characteristics remain unchanged. No impact on reliability is expected.

Current leaded version (leaded die bumps and leaded solder spheres) can still be ordered from e2v until September the 17th 2015 with last shipment possible until September 2016.





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Identification Method to Distinguish Change:

The product change will be identified by a specific package code to distinguish the die bump metallurgy options.

For the lead free solder spheres version

The 'ZJ' package code identifies the full RoHS product with both lead-free die bumps and lead-free solder spheres. Part numbers for such full RoHS product will be PC8548ExZJxxxD

For the leaded solder spheres versions

The existing 'ZF' package code identifying the full leaded product with both leaded die bumps and leaded solder spheres shall be used for placing orders before the last order date herein. Customers shall contact their e2v sales representative for long-term support solutions for this package option.

Also, e2v is introducing the 'ZG' package code to identify products with lead-free die bumps and leaded solder spheres. Part numbers for such configuration will be PC8548ExZGxxxD

Qualification Data for the ZG package option:

available will be available beginning of September 2015 not applicable

ZG package Samples: available will be available Mid-June 2015. not applicable

Quantifiable Impact on Quality & Reliability: *none expected*

Implementation Date*:

Last orders for the ZF package option shall be placed before September 27th, 2015.
Production shipments for the ZG package option are expected to start in October 2015

*The Estimated Implementation Date is the forecasted date that a customer may expect to receive changed product. This is determined by the estimated date of inventory depletion on the PCN issue date. This may be affected by fluctuations in supply and demand. Consequently, although customers should be prepared to receive changed product on this date, e2v semiconductors will continue to ship pre-changed product until a time in which inventory has been depleted. This may result in pre-changed product being shipped to customers after this forecasted date.

e2v semiconductors contact:

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APPROVAL by TRB

e2v semiconductors will deem this change accepted unless specific conditions of acceptance are provided in writing within 30 days from the date of this notice. All correspondence must be sent to the contact e-mail addresses indicated above.

e2v semiconductors assumes no responsibility for any errors that may appear in this document.

The supply of products will be subject to e2v general terms and conditions of sale or any specific contractual terms agreed between the parties.